FOR IMMEDIATE RELEASE

KIC's David Meza to Present SMTA Guadalajara Chapter Webinar on Thermocouple Attachment Methods for Accurate Reflow Profiling

SAN DIEGO, CA – KIC announced that **David Meza, Senior Service Engineer**, will present a live educational webinar hosted by the **SMTA Guadalajara Chapter** titled **"Thermocouples Attachment Methods for Reflow Oven Profiling"** on **Thursday, July 30, 2026**, from **12:00 PM to 1:00 PM (Central Mexico Time)**. Presented in **Spanish**, the complimentary webinar will examine how proper thermocouple attachment techniques can significantly improve the accuracy and reliability of thermal reflow profiles.

Accurate thermal profiles begin with accurate temperature measurements, and one of the most important factors affecting profile quality is how thermocouples are attached to the printed circuit board. During the one-hour session, Meza will explain how proper attachment methods can improve profile reliability, helping manufacturers achieve greater process consistency while reducing defects, rework, and scrap.

Attendees will learn:

- Best practices for improving the accuracy and repeatability of thermal reflow profiles.
- How proper thermocouple attachment methods can reduce defects, rework, and scrap.
- Results from a comparative study evaluating thermocouple attachment methods on modern HDI circuit boards.

With more than eight years at KIC, Meza has worked closely with electronics manufacturers throughout the Americas to optimize SMT processes and improve thermal performance. His expertise includes reflow profiling, wave soldering, thermal process optimization, Industry 4.0 initiatives, and manufacturing performance analysis. He is also an **SMTA Certified Engineer**, helping manufacturers improve quality, productivity, and process control through data-driven thermal optimization.

"Reliable thermal profiles begin with reliable measurements," said Meza. "Understanding how thermocouple attachment methods influence profile accuracy enables manufacturers to make better process decisions and produce more consistent, higher-quality assemblies."

Electronics manufacturing professionals interested in improving thermal process accuracy and reliability are encouraged to attend this free educational session.

Webinar Information

Title: *Thermocouples Attachment Methods for Reflow Oven Profiling*
Presenter: David Meza, Senior Service Engineer, KIC
Host: SMTA Guadalajara Chapter

Date: Thursday, July 30, 2026
Time: 12:00 PM – 1:00 PM (Central Mexico Time)
Language: Spanish
Cost: Complimentary

Registration

Attendance is complimentary, but advance registration is required. For additional information and to register, visit:

https://smta.org/events/EventDetails.aspx?id=2072844&group=225200

Then click the **Register** button to reserve your place.

About KIC

Celebrating 50 years, KIC is a global leader in thermal process intelligence for electronics manufacturing. KIC's innovative solutions help manufacturers optimize thermal processes through **Automatic Profiling**, real-time process monitoring, and the **Thermal Analysis Software (TAS) System**. The company's **Heat to Data™** approach transforms thermal process information into actionable **Thermal Intelligence**, enabling manufacturers to improve product quality, increase productivity, and make smarter manufacturing decisions. With more than **25,000 systems installed worldwide**, KIC continues to help electronics manufacturers achieve greater process control and operational excellence.
